

Title (en)  
PB FREE SOLDER ALLOY

Title (de)  
BLEIFREIE LOTLEGIERUNG

Title (fr)  
ALLIAGE DE SOUDURE SANS PLOMB

Publication  
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Application  
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Abstract (en)  
[origin: WO2006052049A1] The present invention relates to a solder alloy used for mounting or plating electronic components on a printed circuit board (PCB) and the like, and, more particularly, to a Pb-free Sn-Ag based solder alloy which comprises 0.1 ~ 3.0 wt% of Cu, 0.01 ~ 0.5 wt% of Ni, 0.01 ~ 5.0 wt% of Ag, and the balance of Sn. The Pb-free Sn-Ag based solder alloy of the invention has a lower melting point, and highly enhanced wettability and joining strength, compared with the conventional Pb-free solder alloy, thereby preventing generation of bridges.

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